

HSF

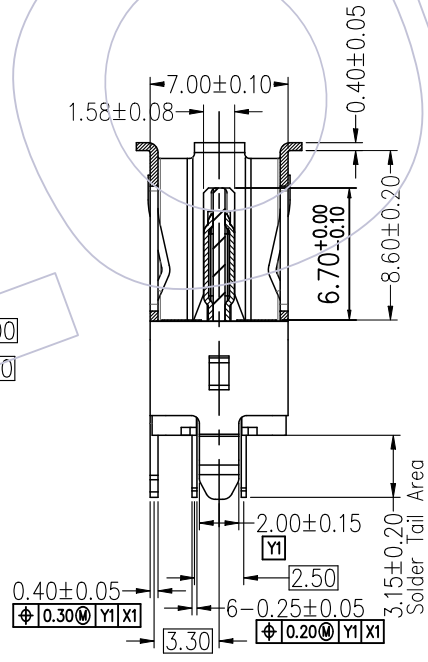
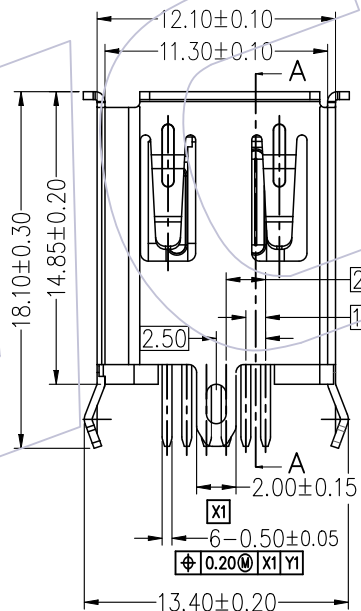
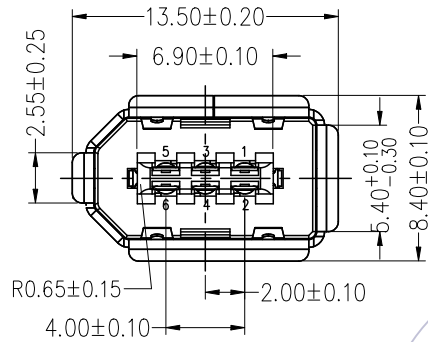
NOTES:

1. Rated Current: 1.0A
2. Contact Resistance: 30mΩ max
3. Withstand Voltage: 500V AC/DC
4. Insulation Resistance: 100MΩ min
5. Operation Temperature: -40°C to +85°C
6. Insulator Material: LCP UL94V-0 BK
7. Terminal/Shell Material: Copper Alloy
8. Terminal Finish:
 - XXu" Gold on Contact Area (see ordering information)
 - 80u" Min. Sn on Solder Tails area
 - 50u" Ni underplating overall
9. Shell Finish: 30u" Min. Ni Underplating Over All.
10. Soldering: Solder temperature: 245+/-3°C
Solder time: 3-5 S

Ordering Information

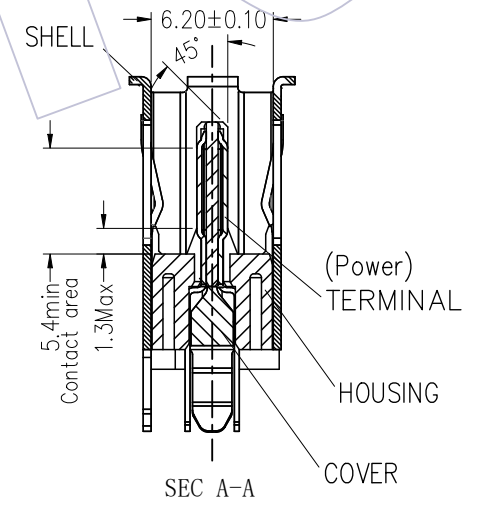
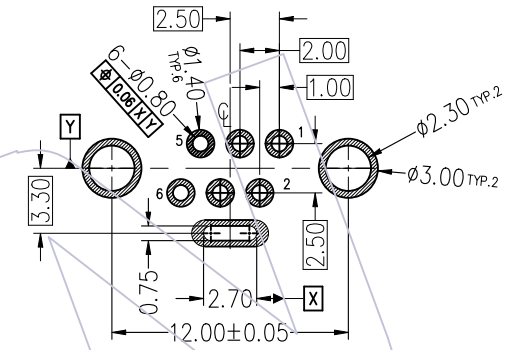
6130 - 06 M S SX D B N A I

- Pin 06=6P
- Type M=Male
- Join Type S=180° DIP
- Contact Plating S0=Gold Flash/Tin S1=3u"Gold/Tin
- Wcon Internal Code
- Package A=Tray
- Post N=W/O
- Insulator Color B=Black
- Insulator Material D=LCP



Recommended P.C.B Layout (Top Side)

(PCB BOARD TOLERANCE ±0.03)



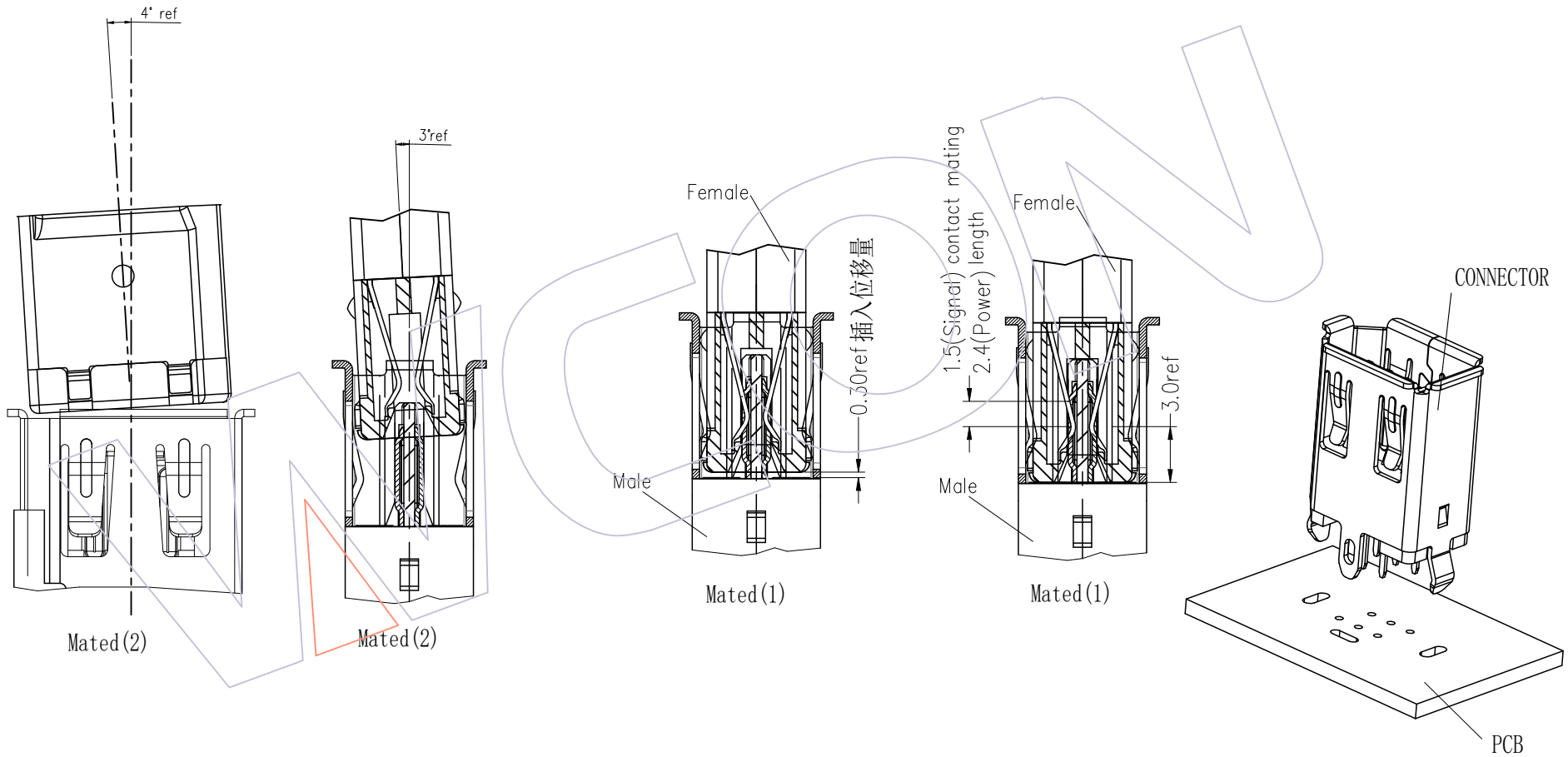
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	OPERATION	DRAW	DATE	SCALE	FIT	PART NO.
A0	2020/04/20	NEW	Morris	x.x ±0.40	Morris	2020/04/20	UNIT mm		6130-06MSSXDBNA1
				x.xx ±0.25	CHECK	DATE	SIZE A4		TITLE:
				x.xxx ±0.15			SHEET 1/1		2.0mm SIC Male 180° DIP 6P
				Angle ± 3°	APPROVE	DATE	PROJ.		Customer NO.
				DIM TOL					

WCON

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				OPERATION	DRAW	DATE	SCALE	FIT	PART NO.
				x.x ±0.40	Morris	2020/04/20	UNIT	mm	6130-06MSSXDBNA1
				x.xx ±0.25	CHECK	DATE	SIZE	A4	TITLE:
A0	2020/04/20	NEW	Morris	x.xxx ±0.15	APPROVE	DATE	SHEET	2/2	2.0mm SIC Male 180° DIP 6P
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	Angle ± 3°			PROJ.	⌀	Customer NO.
				DIM TOL					

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